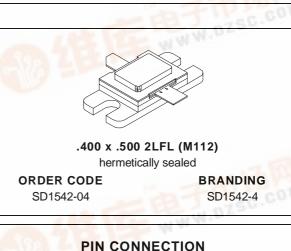
SGS-THOMSON MICROELECTRONICS

SD1542-04

RF & MICROWAVE TRANSISTORS AVIONICS APPLICATIONS

- DESIGNED FOR HIGH POWER PULSED IFF
- 600 WATTS (min.) IFF 1030/1090 MHz
- REFRACTORY GOLD METALLIZATION
- 6.0 dB MIN. GAIN
- BALLASTING AND LOW THERMAL
 REISTANCE FOR RELIABILITY AND RUGGEDNESS
- 30:1 LOAD VSWR CAPABILITY AT SPECIFIED OPERATING CONDITIONS
- INPUT MATCHED, COMMON BASE CONFIGURATION



DESCRIPTION

The SD1542-04 is a hermetically sealed, gold metallized, silicon NPN power transistor. The SD1542-04 is designed for applications requiring high peak power and low duty cycles such as IFF. The SD1542-04 is packaged in a hermetic metal/ceramic package with internal input matching, resulting in improved broadband performance and low thermal reistance.

led, gold me-The SD1542ng high peak as IFF. The tric metal/cematching, reprmance and 1. Collector 3. Emitter 2. Base 4. Base

ABSOLUTE MAXIMUM RATINGS ($T_{case} = 25^{\circ}C$)

Symbol	Parameter	Value	Unit V	
Vсво	Collector-Base Voltage	65		
VCES	Collector-Emitter Voltage	65	V	
VEBO	Emitter-Base Voltage	3.5	V	
lc	Device Current	40	А	
PDISS	Power Dissipation	1350	W	
TJ	Junction Temperature	+200	°C	
T _{STG}	Storage Temperature	– 65 to +150	°C	

THERMAL DATA

R _{TH(j-c)} Junction-Case Thermal Resistance	0.06	°C/W
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SD1542-04

ELECTRICAL SPECIFICATIONS ($T_{case} = 25^{\circ}C$)

STATIC

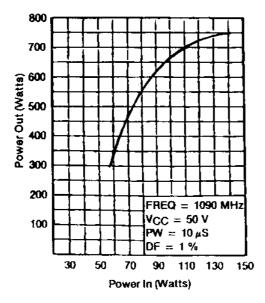
Symbol	Test Conditions		Value			Unit	
		М	lin.	Тур.	Max.	om	
ВУсво	$I_C = 25 mA$	$I_E = 0 m A$	e	65	_		V
BV _{EBO}	$I_E = 10 mA$	$I_{C} = 0 m A$	3	3.5	_	_	V
ICES	$V_{CE} = 50V$	$I_E = 0 m A$	-			35	mA
h _{FE}	$V_{CE} = 5V$	$I_C = 1A$		5	_	200	

DYNAMIC

Symbol	Test Conditions			Value			
Symbol	Test conditions			Min.	Тур.	Max.	Unit
Pout	f = 1090 MHz	$P_{IN} = 150 \text{ W}$	$V_{\text{CE}} = 50 \ \text{V}$	600	—	_	W
GP	f = 1090 MHz	$P_{IN} = 150 \text{ W}$	$V_{CE} = 50 V$	6.0	—		dB

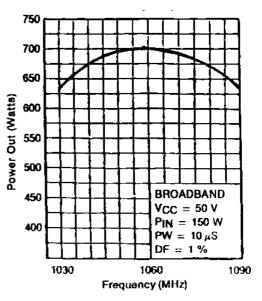
Note: Pulse Width = 10μ Sec, Duty Cyle = 1%

TYPICAL PERFORMANCE



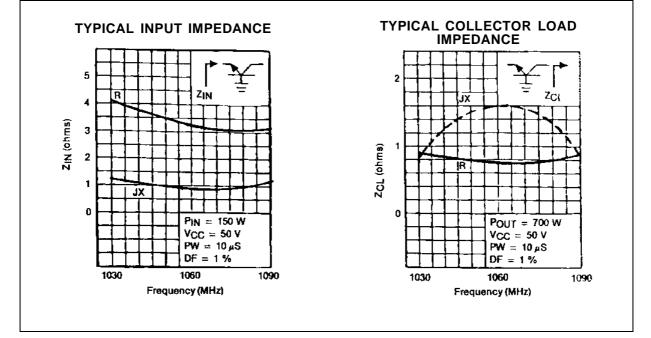
POWER OUTPUT vs POWER INPUT

POWER OUTPUT vs FREQUENCY



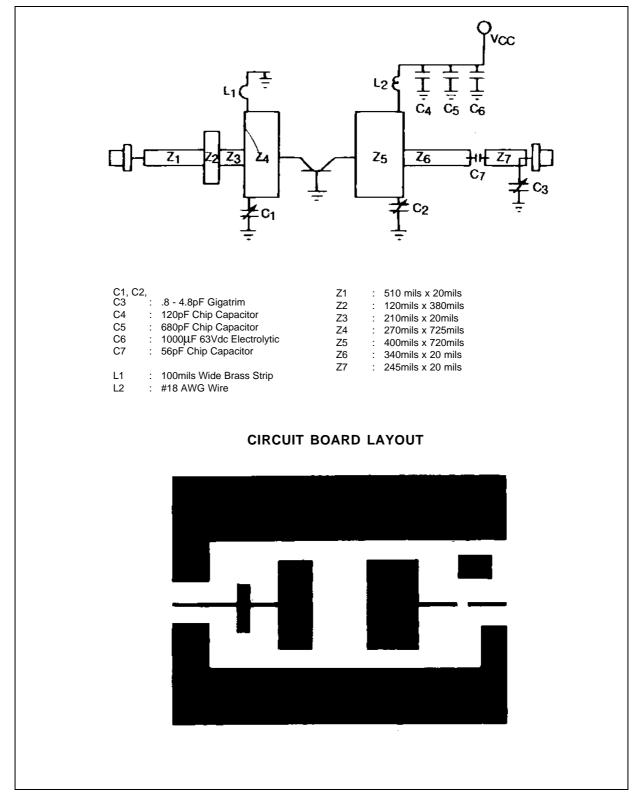


IMPEDANCE DATA



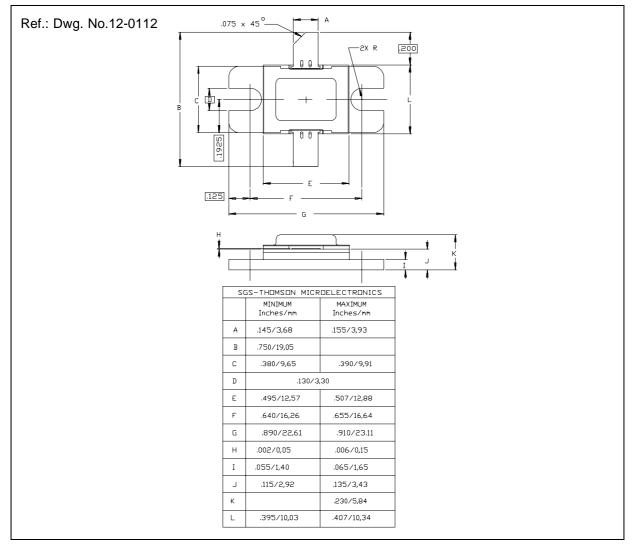


TEST CIRCUIT





PACKAGE MECHANICAL DATA



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